

GENERAL PURPOSE OPERATIONAL AMPLIFIER

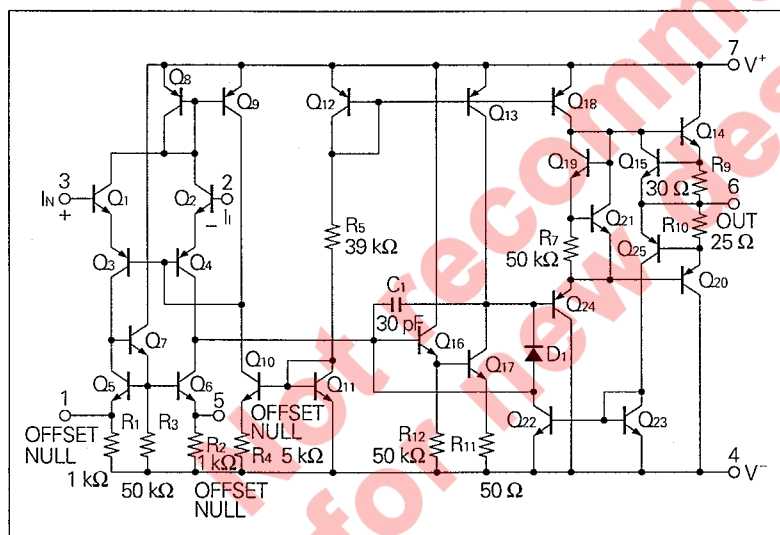
DESCRIPTION

The μPC741 is a general purpose operational amplifier having internal frequency compensating circuits. It is intended for a wide range of analog applications. High common mode voltage range and no latch up tendencies make this amplifier ideal for use as a voltage follower.

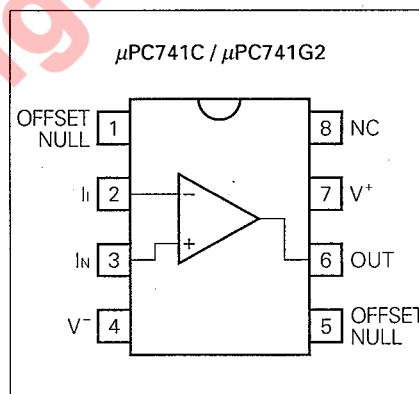
FEATURES

- Internal frequency compensation
- Short circuit protection
- Offset voltage null capability

EQUIVALENT CIRCUIT



CONNECTION DIAGRAM
(Top View)



ORDERING INFORMATION

PART NUMBER	PACKAGE	QUALITY GRADE
μPC741C	8 PIN PLASTIC DIP (300 mil)	Standard
μPC741G2	8 PIN PLASTIC SOP (225 mil)	Standard

Please refer to "Quality grade on NEC Semiconductor Devices" (Document number IEI-1209) published by NEC Corporation to know the specification of quality grade on the devices and its recommended applications.

ABSOLUTE MAXIMUM RATINGS (T_a = 25 °C)

PARAMETER		SYMBOL	μPC741	UNIT
Voltage between V ⁺ and V ⁻ (Note 1)		V ⁺ - V ⁻	-0.3 to +36	V
Differential Input Voltage		V _{ID}	±30	V
Input Voltage (Note 2)		V _I	V ⁻ -0.3 to V ⁺ +0.3	V
Output Voltage (Note 3)		V _O	V ⁻ -0.3 to V ⁺ +0.3	V
Power Dissipation	C Package (Note 4)	P _T	350	mW
	G2 Package (Note 5)		440	mW
Output Short Circuit Duration (Note 6)			Indefinite	sec
Voltage between Offset-Null and V ⁺			±0.5	V
Operating Temperature Range		T _{opt}	-20 to +80	°C
Storage Temperature Range		T _{stg}	-55 to +125	°C

Note 1. Reverse connection of supply voltage can cause destruction.

Note 2. The input voltage should be allowed to input without damage or destruction. Even during the transition period of supply voltage, power on/off etc., this specification should be kept. The normal operation will establish when the both inputs are within the Common Mode Input Voltage Range of electrical characteristics.

Note 3. This specification is the voltage which should be allowed to supply to the output terminal from external without damage or destructive. Even during the transition period of supply voltage, power on/off etc., this specification should be kept. The output voltage of normal operation will be the Output Voltage Swing of electrical characteristics.

Note 4. Thermal derating factor is -5.0 mW / °C when ambient temperature is higher than 55 °C.

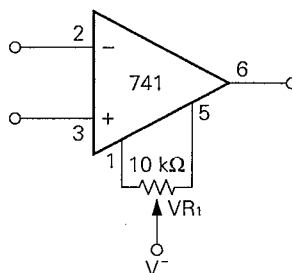
Note 5. Thermal derating factor is -4.4 mW / °C when ambient temperature is higher than 25 °C.

Note 6. Pay careful attention to the total power dissipation not to exceed the absolute maximum ratings, Note 4 and Note 5.

RECOMMENDED OPERATING CONDITIONS

CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply Voltage (Split)	V [±]	± 7.5		± 16	V
Supply Voltage (V ⁻ = GND)	V ⁺	+ 15		+ 32	V
Output Current	I _O		± 2	± 5	mA

OFFSET VOLTAGE NULL CIRCUIT



ELECTRICAL CHARACTERISTICS (T_a = 25 °C, V[±] = ±15 V)

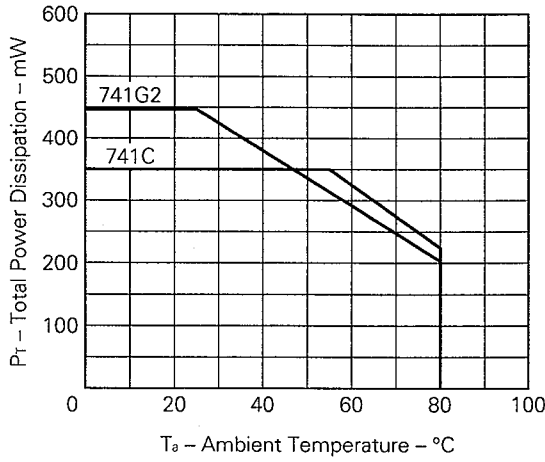
CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS
Input Offset Voltage	V _{io}		±1.0	±6.0	mV	R _s ≤ 10 kΩ
Average V _{io} Temperature Drift	ΔV _{io} /ΔT		±3	±30	μV/°C	R _s ≤ 10 kΩ
Input Offset Current (Note 7)	I _{io}		±20	±200	nA	
Input Bias Current (Note 7)	I _b		80	500	nA	
Large Signal Voltage Gain	A _v	25000	200000			R _L ≥ 2 kΩ, V _o = ±10 V
Offset Voltage Adjustable Range			±15		mV	VR ₁ = 10 kΩ
Supply Current	I _{cc}		1.5	2.8	mA	I _o = 0 A
Power Consumption	P _d		45	85	mW	I _o = 0 A
Common Mode Rejection Ratio	CMR	70	90		dB	R _s ≤ 10 kΩ
Supply Voltage Rejection Ratio	SVR		30	150	μV/V	R _s ≤ 10 kΩ
Output Voltage Swing	V _{om}	±12	+14 -12		V	R _L ≥ 10 kΩ
		±10	+13 -11			R _L ≥ 2 kΩ
Common Mode Input Voltage Range	V _{icm}		V ⁺ -0.5 V ⁻ +2		V	
Output Short Circuit Current	I _{o short}	5	20		mA	R _L = 0

Note 7. Input bias currents flow into IC. Because each currents are base current of NPN-transistor on input stage.

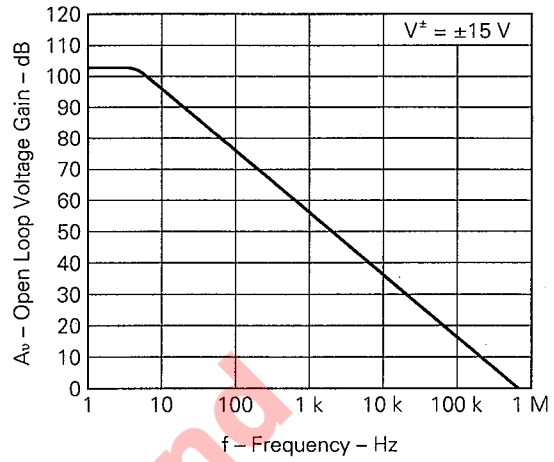
Not recommended for new design

TYPICAL PERFORMANCE CHARACTERISTICS ($T_a = 25^\circ\text{C}$, TYP.)

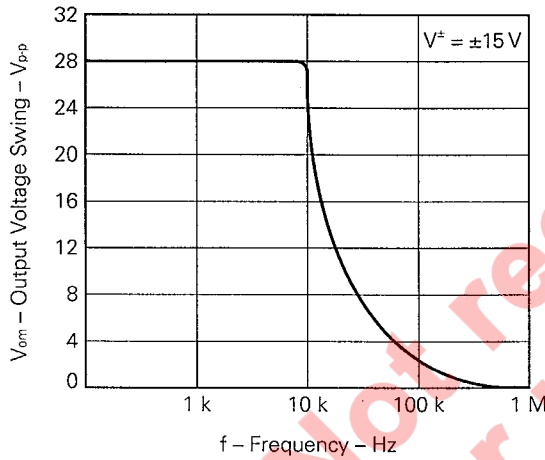
POWER DISSIPATION



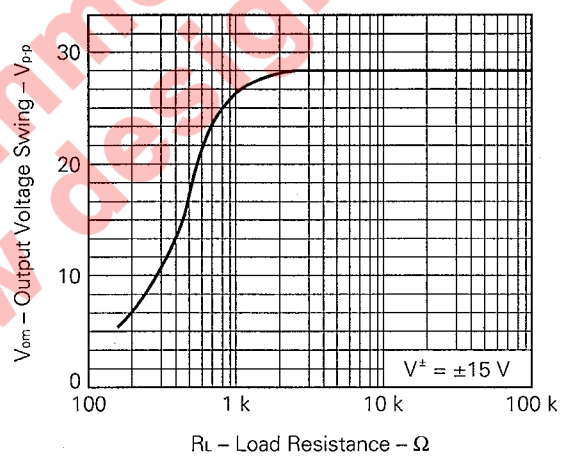
OPEN LOOP FREQUENCY RESPONSE



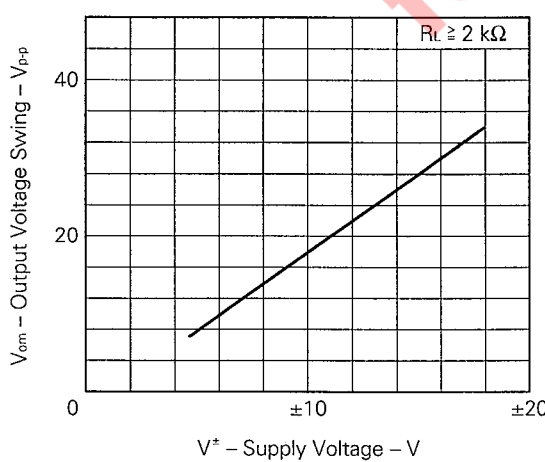
LARGE SIGNAL FREQUENCY RESPONSE



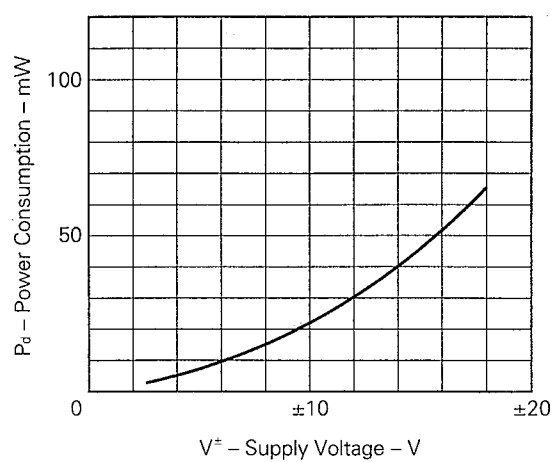
OUTPUT VOLTAGE SWING

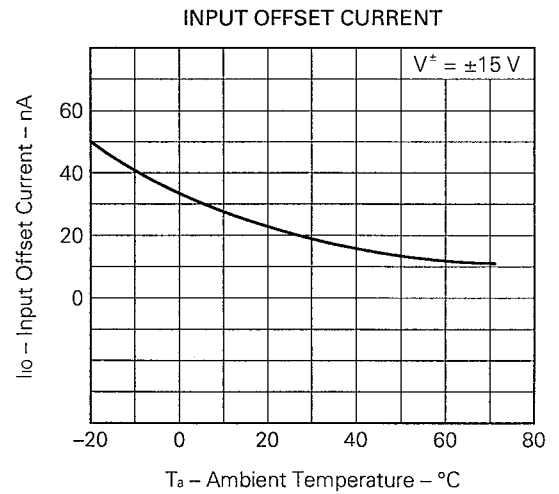
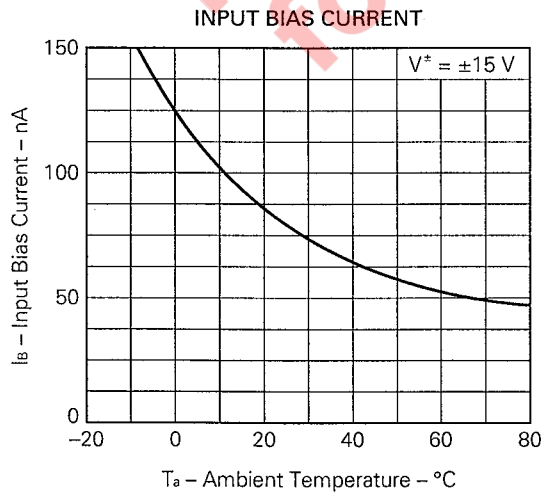
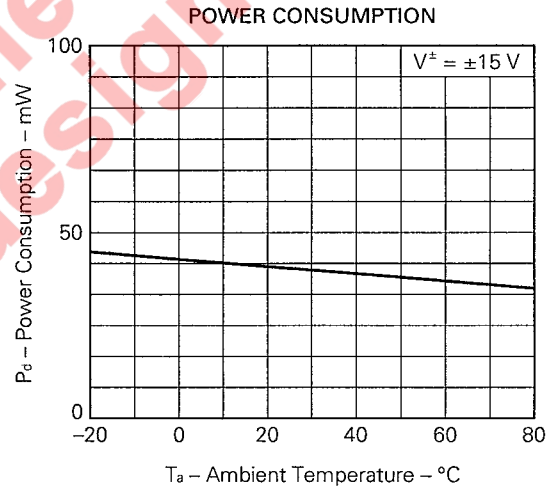
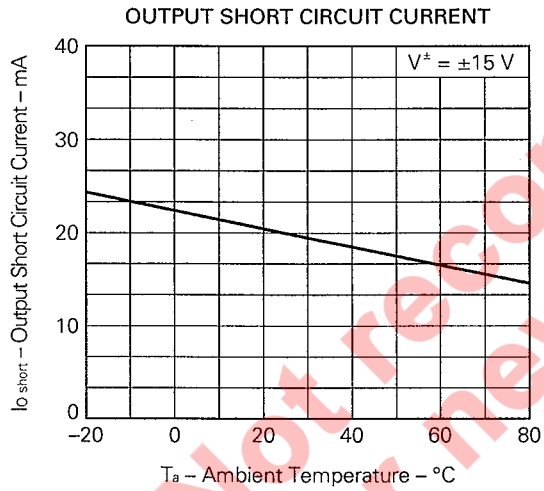
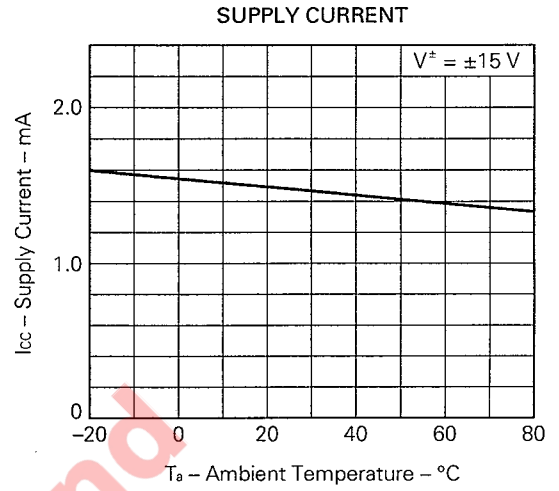
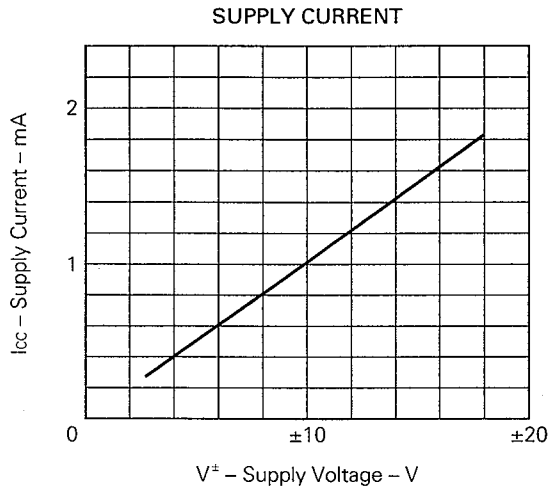


OUTPUT VOLTAGE SWING

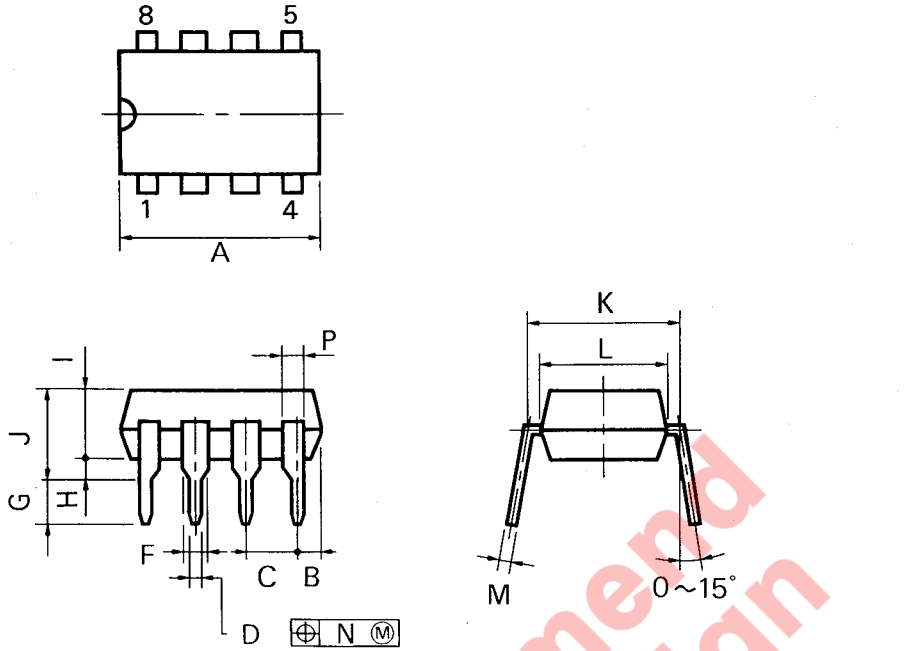


POWER CONSUMPTION





8PIN PLASTIC DIP (300 mil)

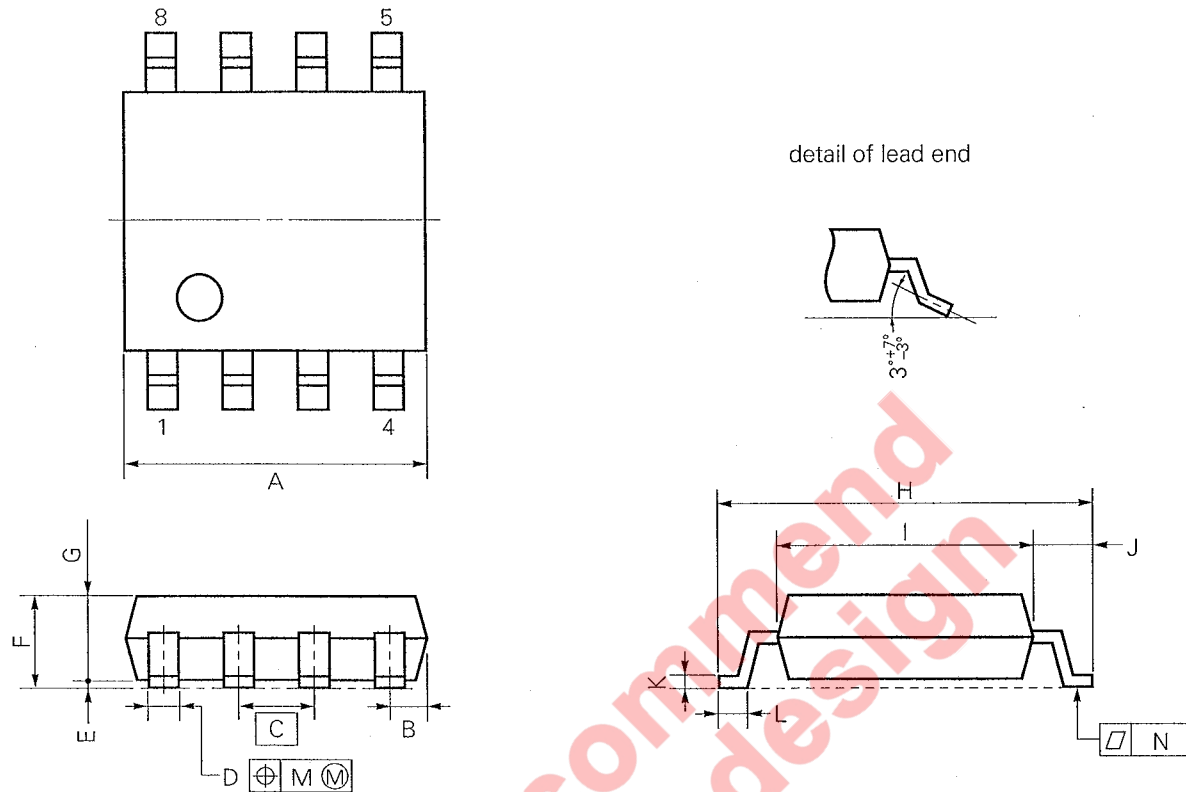


NOTES

- 1) Each lead centerline is located within 0.25 mm (0.01 inch) of its true position (T.P.) at maximum material condition.
- 2) Item "K" to center of leads when formed parallel.

ITEM	MILLIMETERS	INCHES
A	10.16 MAX.	0.400 MAX.
B	1.27 MAX.	0.050 MAX.
C	2.54 (T.P.)	0.100 (T.P.)
D	0.50 ^{+0.10}	0.020 ^{+0.004}
F	1.4 MIN.	0.055 MIN.
G	3.2 ^{±0.3}	0.126 ^{±0.012}
H	0.51 MIN.	0.020 MIN.
I	4.31 MAX.	0.170 MAX.
J	5.08 MAX.	0.200 MAX.
K	7.62 (T.P.)	0.300 (T.P.)
L	6.4	0.252
M	0.25 ^{+0.10} _{-0.05}	0.010 ^{+0.004} _{-0.003}
N	0.25	0.01
P	0.9 MIN.	0.035 MIN.

8 PIN PLASTIC SOP (225 mil)



NOTE

Each lead centerline is located within 0.12 mm (0.005 inch) of its true position (T.P.) at maximum material condition.

S8GM-50-225B-2

ITEM	MILLIMETERS	INCHES
A	5.37 MAX.	0.212 MAX.
B	0.78 MAX.	0.031 MAX.
C	1.27 (T.P.)	0.050 (T.P.)
D	0.40 ^{+0.10} _{-0.05}	0.016 ^{+0.004} _{-0.003}
E	0.1±0.1	0.004±0.004
F	1.8 MAX.	0.071MAX.
G	1.49	0.059
H	6.5±0.3	0.256±0.012
I	4.4	0.173
J	1.1	0.043
K	0.15 ^{+0.10} _{-0.05}	0.006 ^{+0.004} _{-0.002}
L	0.6±0.2	0.024 ^{+0.008} _{-0.009}
M	0.12	0.005
N	0.15	0.006

RECOMMENDED SOLDERING CONDITIONS

The following conditions (see table below) must be met when soldering this product.
Please consult with our sales offices in case other soldering process is used, or in case soldering is done under different conditions.

TYPES OF SURFACE MOUNT DEVICE

For more details, refer to our document "SEMICONDUCTOR DEVICE MOUNTING TECHNOLOGY MANUAL" (IEI-1207).

[μPC741G2]

Soldering method	Soldering conditions	Recommended condition symbol
Infrared ray reflow	Peak package's surface temperature: 230 °C or below, Reflow time: 30 seconds or below (210 °C or higher), Number of reflow process: 1, Exposure limit*: None	IR30-00-1
VPS	Peak package's surface temperature: 215 °C or below, Reflow time: 40 seconds or below (200 °C or higher), Number of reflow process: 1, Exposure limit*: None	VP15-00-1
Wave soldering	Solder temperature: 260 °C or below, Flow time: 10 seconds or below, Number of flow process: 1, Exposure limit*: None	WS15-00-1
Partial heating method	Terminal temperature: 300 °C or below, Flow time: 10 seconds or below, Exposure limit*: None	

*: Exposure limit before soldering after dry-pack package is opened.
Storage conditions: 25 °C and relative humidity at 65 % or less.

Note: Do not apply more than a single process at once, except for "Partial heating method."

TYPES OF THROUGH HOLE DEVICE

[μPC741C]

Soldering method	Soldering conditions	Recommended condition symbol
Wave soldering	Solder temperature: 260 °C or below, Flow time: 10 seconds or below	

[MEMO]

**Not recommend
for new design**

[MEMO]

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Application examples recommended by NEC Corporation.

Standard: Computer, Office equipment, Communication equipment, Test and Measurement equipment, Machine tools, Industrial robots, Audio and Visual equipment, Other consumer products, etc.

Special: Automotive and Transportation equipment, Traffic control systems, Antidisaster systems, Anticrime systems, etc.